



Sheet 1 of 1

Form 1449*	Atty. Docket No.: 303.356US1	Serial No. 08/902,133
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	Applicant: Leonard Forbes et al.	
	Filing Date: July 29, 1997	Group: 2815

U.S. PATENT DOCUMENTS

**Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
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JSE	4,841,349	06/20/1989	Nakano, M.	257 257	2075	10/28/87
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**Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation Yes No
JSE	01-115162	05/08/1989	Japan	H01L	29/78	
JSE	0291951	11/23/1988	European	H01L	29/64	
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OTHER DOCUMENTS

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JSE	Zirinsky, S., et al., "Electrical Resistivity of Amorphous Silicon Resistor Films", <u>Extended Abstracts of the Spring Meeting of the Electrochemical Society</u> , Washington, DC, pp. 147-149, (1971)

Examiner <u>JSE</u>	Date Considered <u>4/10/01</u>
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*Substitute Disclosure Statement Form (PTO-1449)

**EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.